

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
JUNGBAE LEE	06/10/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	MICRON TECHNOLOGY, INC.
<b>Street Address:</b>	8000 S. FEDERAL WAY
<b>Internal Address:</b>	P.O. BOX 6
<b>City:</b>	BOISE
<b>State/Country:</b>	IDAHO
<b>Postal Code:</b>	83707-0006
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17732276
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(206)359-4461
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	206-359-8000
<b>Email:</b>	patentprocurement@perkinscoie.com
<b>Correspondent Name:</b>	PERKINS COIE LLP - MICRON PATENT-SEA
<b>Address Line 1:</b>	PO BOX 1247
<b>Address Line 4:</b>	SEATTLE, WASHINGTON 98111-1247
<b>ATTORNEY DOCKET NUMBER:</b>	010829-9487.US01
<b>NAME OF SUBMITTER:</b>	SAM BEARD
<b>SIGNATURE:</b>	/Sam Beard/
<b>DATE SIGNED:</b>	04/28/2022
<b>Total Attachments: 2</b>	
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source=2022-04-28 Assignment as Filed (010829-9487.US01)#page2.tif	

## ASSIGNMENT BY INVENTORS

This Assignment is by the following individuals (the "Assignors"):

- **Jungbae Lee**, having a mailing address of c/o Micron Technology, Inc., 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006.

The Assignors invented one or more certain inventions (the "Invention(s)") described in an application for Letters Patent of the United States titled SEMICONDUCTOR DEVICE ASSEMBLIES WITH CONDUCTIVE UNDERFILL DAMS FOR GROUNDING EMI SHIELDS AND METHODS FOR MAKING THE SAME, naming the Assignors as inventors, and filed on \_\_\_\_\_ as U.S. Application No. \_\_\_\_\_ (the "Application"). The Assignors authorize the Assignee, identified below, or its representatives to insert the application number and filing date of the Application when known.

Micron Technology, Inc., a corporation of Delaware having its principal place of business at 8000 S. Federal Way, P.O. Box 6, Boise, Idaho 83707-0006 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which Assignors acknowledge, Assignors hereby sell, assign, and transfer to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignors warrant that Assignors own the Rights, and that the Rights are unencumbered. Assignors also agree to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignors request the Commissioner of Patents to issue any

Patent of the United States that may be issued on the Invention(s) to Assignee. This Assignment may be executed in counterparts.

Date:

2020/6/10



Jungbae Lee